# **<u>MOSFET</u>** – Power, Single, N-Channel 60 V, 1.3 mΩ, 250 A

### Features

- Small Footprint (5x6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V <sub>DSS</sub>	60	V
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V
Continuous Drain		$T_{C} = 25^{\circ}C$	۱ <sub>D</sub>	250	А
Current R <sub>θJC</sub> (Notes 1, 3)	Steady	T <sub>C</sub> = 100°C		160	
Power Dissipation $R_{\theta JC}$ (Note 1)	State	$T_{C} = 25^{\circ}C$	PD	160	W
		T <sub>C</sub> = 100°C		63	
Continuous Drain		T <sub>A</sub> = 25°C	۱ <sub>D</sub>	35	А
Current R <sub>θJA</sub> (Notes 1, 2, 3)	Steady	T <sub>A</sub> = 100°C		22	
Power Dissipation	State	T <sub>A</sub> = 25°C	PD	3.3	W
$R_{\theta JA}$ (Notes 1, 2)		T <sub>A</sub> = 100°C		1.3	
Pulsed Drain Current	$T_A = 25^{\circ}C$ , $t_p = 10 \ \mu s$		I <sub>DM</sub>	900	А
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>stg</sub>	–55 to + 150	°C
Source Current (Body Diode)			I <sub>S</sub>	170	А
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 26 A)			E <sub>AS</sub>	338	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	0.80	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	38	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.

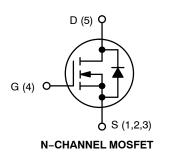
3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

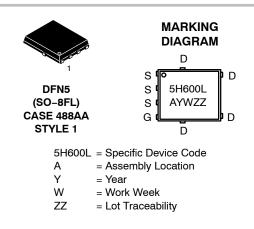


# **ON Semiconductor®**

## www.onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
60 V	1.3 m $\Omega$ @ 10 V	050 4
00 V	1.7 mΩ @ 4.5 V	250 A





# **ORDERING INFORMATION**

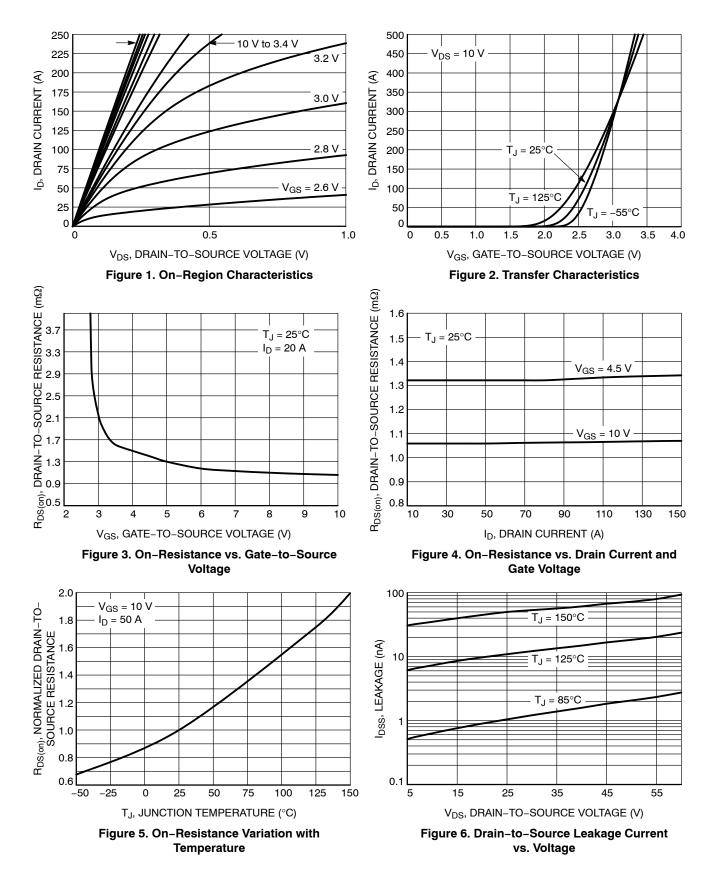
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

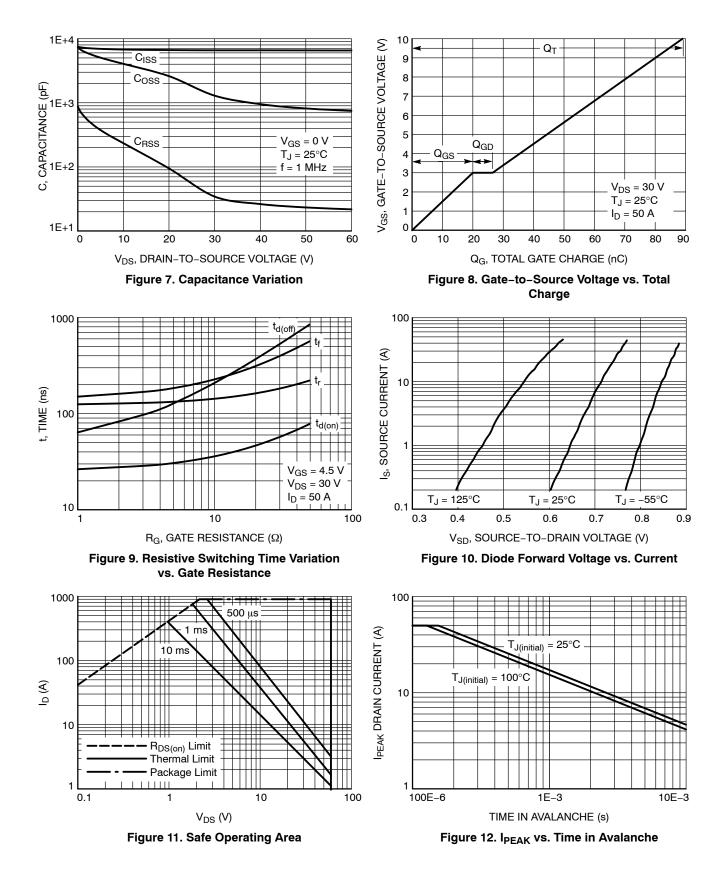
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu$ A		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> / TJ				34.3		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$ , $T_J = 25 °C$				10	
		$V_{DS} = 60 \text{ V}$ $T_{J} = 125^{\circ}\text{C}$	T <sub>J</sub> = 125°C			250	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = 20 V				100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{D}$	= 250 μA	1.2		2.0	V
Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				-5.0		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 50 A		1.1	1.3	
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 50 A		1.4	1.7	mΩ
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> =15 V, I	<sub>D</sub> = 50 A		280		S
CHARGES, CAPACITANCES & GATE RE	SISTANCE						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 30 V			6680		
Output Capacitance	C <sub>OSS</sub>				1230		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>				30		
Output Charge	Q <sub>OSS</sub>	$V_{GS} = 0 \text{ V}, V_{DD} = 30 \text{ V}$ $V_{GS} = 4.5 \text{ V}, V_{DS} = 30 \text{ V}; \text{ I}_{D} = 50 \text{ A}$ $V_{GS} = 10 \text{ V}, V_{DS} = 30 \text{ V}; \text{ I}_{D} = 50 \text{ A}$			100		
Total Gate Charge	Q <sub>G(TOT)</sub>				40		nC V
Total Gate Charge	Q <sub>G(TOT)</sub>				89		
Threshold Gate Charge	Q <sub>G(TH)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 30 V; I <sub>D</sub> = 50 A			11		
Gate-to-Source Charge	Q <sub>GS</sub>				20		
Gate-to-Drain Charge	Q <sub>GD</sub>				6.5		
Plateau Voltage	V <sub>GP</sub>				3.0		
SWITCHING CHARACTERISTICS (Note §	5)						
Turn-On Delay Time	t <sub>d(ON)</sub>				29.8		
Rise Time	t <sub>r</sub>	V <sub>GS</sub> = 4.5 V, V	= 30 V,		20.7		1
Turn-Off Delay Time	t <sub>d(OFF)</sub>	$\begin{array}{l} V_{\mathrm{GS}} = 4.5 \ V, \ V_{\mathrm{DS}} = 30 \ V, \\ I_{\mathrm{D}} = 50 \ A, \ R_{\mathrm{G}} = 2.5 \ \Omega \end{array}$			41.6		- ns
Fall Time	t <sub>f</sub>				14.1		
DRAIN-SOURCE DIODE CHARACTERIS	TICS			-	-		-
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V,	$T_J = 25^{\circ}C$		0.77	1.2	
		I <sub>S</sub> = 50 A	$T_J = 125^{\circ}C$		0.63 V		
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, dI <sub>S</sub> /dt = 100 A/µs, I <sub>S</sub> = 50 A			72		
Charge Time	t <sub>a</sub>				36		ns
Discharge Time	t <sub>b</sub>				36		1
Reverse Recovery Charge	Q <sub>RR</sub>				60		nC

performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width  $\leq 300 \ \mu$ s, duty cycle  $\leq 2\%$ . 5. Switching characteristics are independent of operating junction temperatures.

# **TYPICAL CHARACTERISTICS**



# **TYPICAL CHARACTERISTICS**



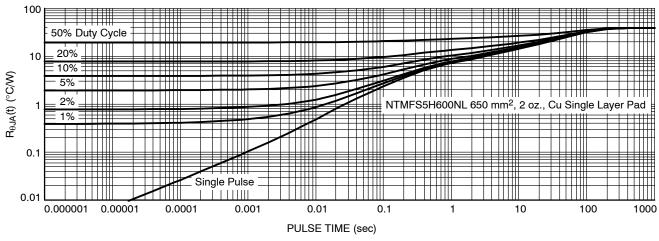


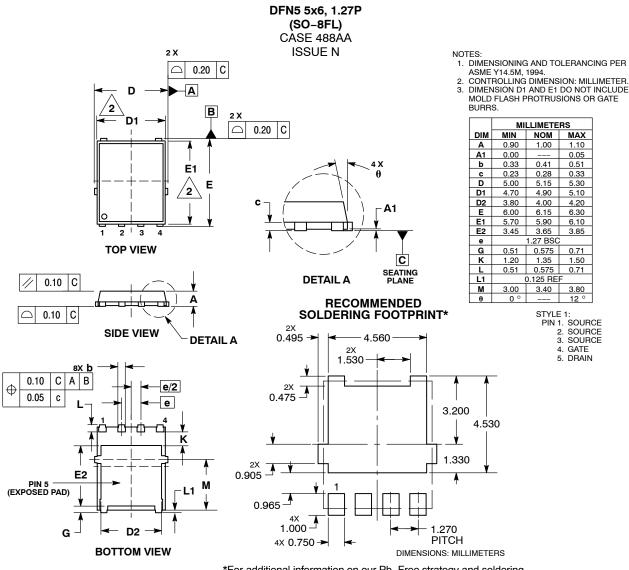
Figure 13. Thermal Characteristics	Figure 13	. Thermal	Characteristics
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# **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NTMFS5H600NLT1G	5H600L	DFN5 (Pb–Free)	1500 / Tape & Reel
NTMFS5H600NLT3G	5H600L	DFN5 (Pb–Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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#### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT

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